

PRODUCT / PROCESS CHANGE NOTIFICATION

1. PCN basic data

1.1 Company		STMicroelectronics International N.V
1.2 PCN No.	AMS/16/9620	
1.3 Title of PCN	Product Change Notification on the Standardization of the backside coating thickness for wafer level CSP	
1.4 Product Category	See product list	
1.5 Issue date	2016-02-22	

2. PCN Team

2.1 Contact supplier	
2.1.1 Name	ROBERTSON HEATHER
2.1.2 Phone	+1 8475853058
2.1.3 Email	heather.robertson@st.com
2.2 Change responsibility	
2.2.1 Product Manager	Andrea Mario ONETTI
2.1.2 Marketing Manager	Lionel GRILLO,Wing-Sze LEE
2.1.3 Quality Manager	Jean-Marc BUGNARD,Giuseppe LISI

3. Change

3.1 Category	3.2 Type of change	3.3 Manufacturing Location
Wafer Fab (Process)	Backside finish modification except for wafer for sale: change in deposition material type/nature or final thickness	ST Shenzen

4. Description of change

	Old	New
4.1 Description	Back coating thickness is 50µm or 25µm depending on the product	Back coating thickness will be standardized to 25µm
4.2 Anticipated Impact on form,fit, function, quality, reliability or processability?	No impact on form, fit, function, reliability, or processability	

5. Reason / motivation for change

5.1 Motivation	The standardization of the material used for package assembly will secure the purchasing of the direct material and improve the service to ST Customers for the affected package.
5.2 Customer Benefit	SERVICE IMPROVEMENT

6. Marking of parts / traceability of change

6.1 Description	Full traceability will be ensured thanks to traceability code and Bulk Id.
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7. Timing / schedule

7.1 Date of qualification results	2016-01-15
7.2 Intended start of delivery	2016-03-31
7.3 Qualification sample available?	Upon Request

8. Qualification / Validation

8.1 Description	qual report backcoating 25.pdf		
8.2 Qualification report and qualification results	Available (see attachment)	Issue Date	2016-02-22

9. Attachments (additional documentations)

9620PpPrdtLst.pdf
qual report backcoating 25.pdf

10. Affected parts

10. 1 Current		10.2 New (if applicable)
10.1.1 Customer Part No	10.1.2 Supplier Part No	10.1.2 Supplier Part No
	GG25LAJ	
	GG25LJ	
	STC3115AIJT	
	STC3115IJT	
	STC3117IJT	
	STG3820BJR	



Public Products List

PCN Title : Product Change Notification on the Standardization of the backside coating thickness for wafer level CSP

PCN Reference : AMS/16/9620

PCN Created on : 21-Jan-2016

Subject : Public Products List

Dear Customer,

Please find below the Standard Public Products List impacted by the change.

STC3115AIJT	TS922EIJT	GG25LAJ
STMPE1801BJR	STG3820BJR	STC3117IJT
GG25LJ	STC3115IJT	



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